

Fig. 1

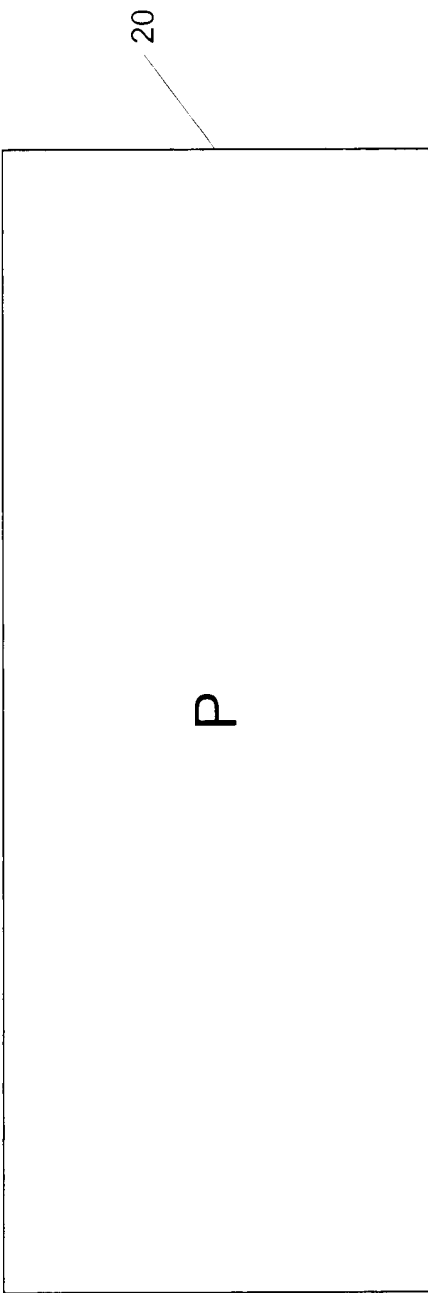


Fig. 2a

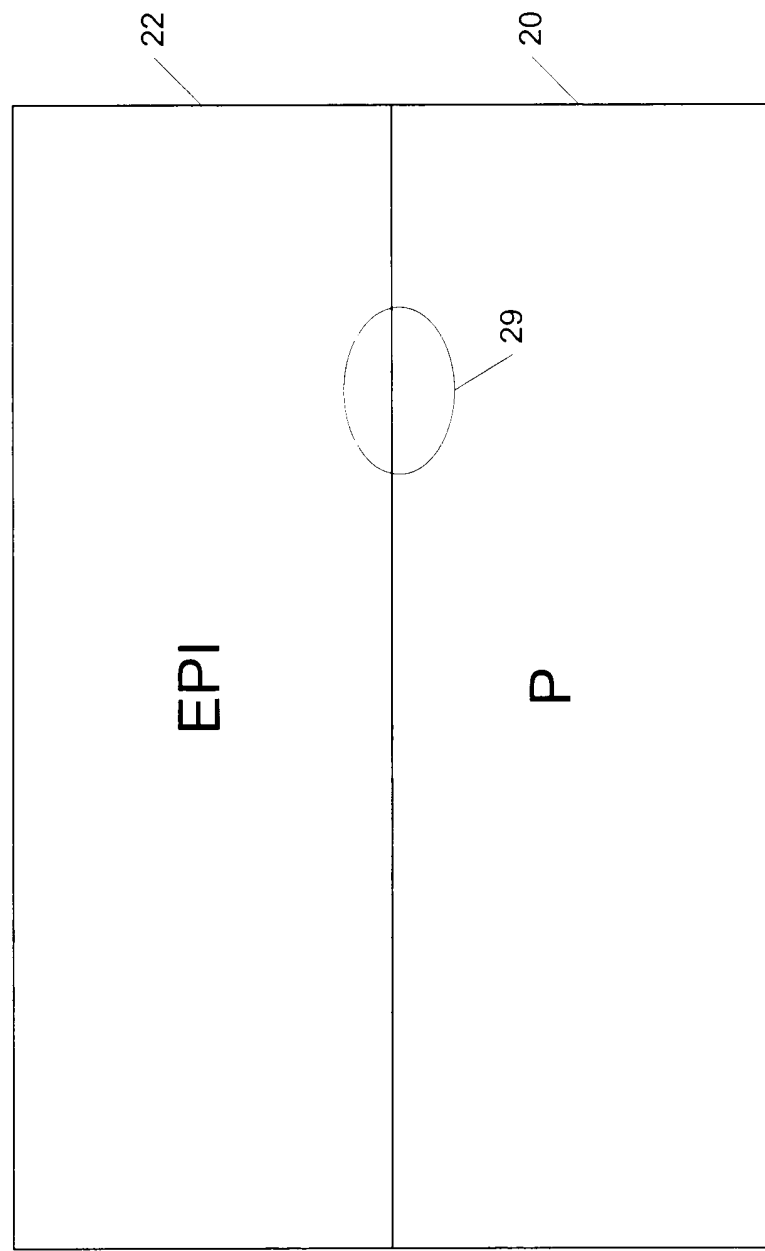


Fig. 2b

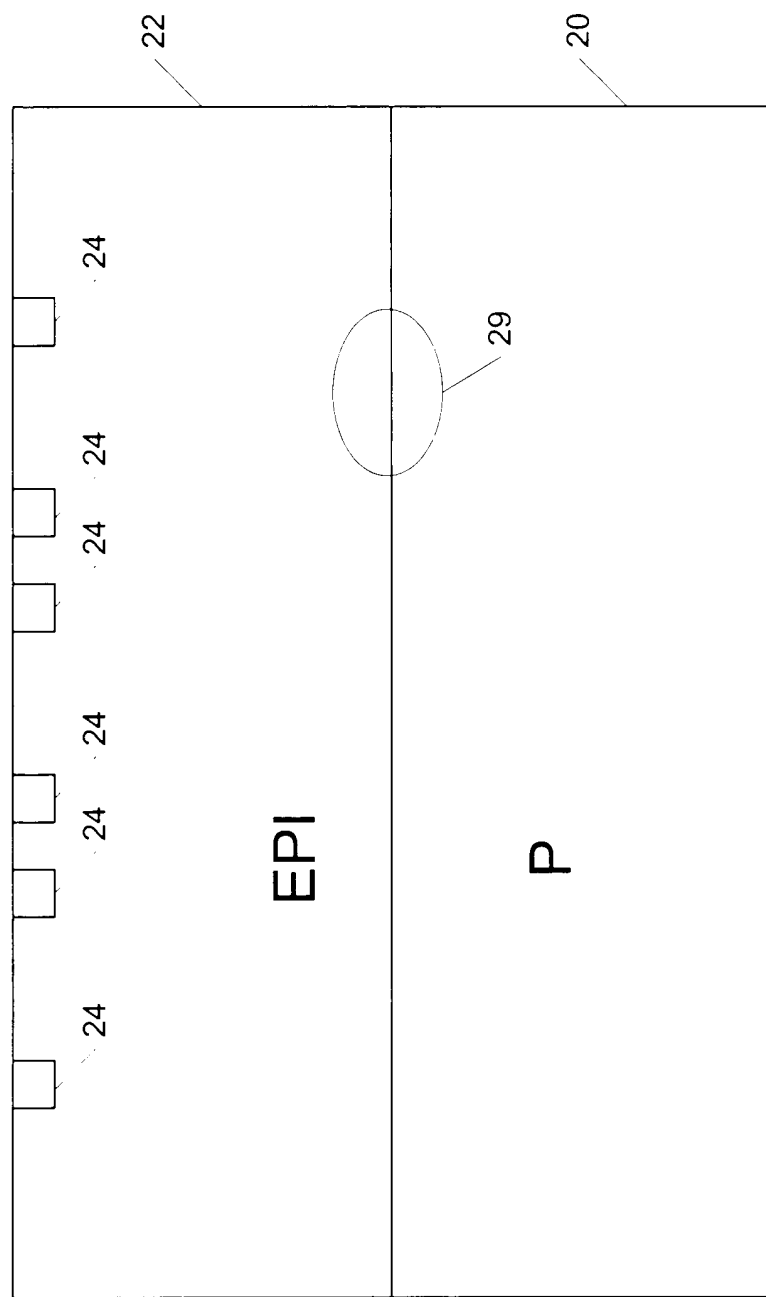


Fig. 2c

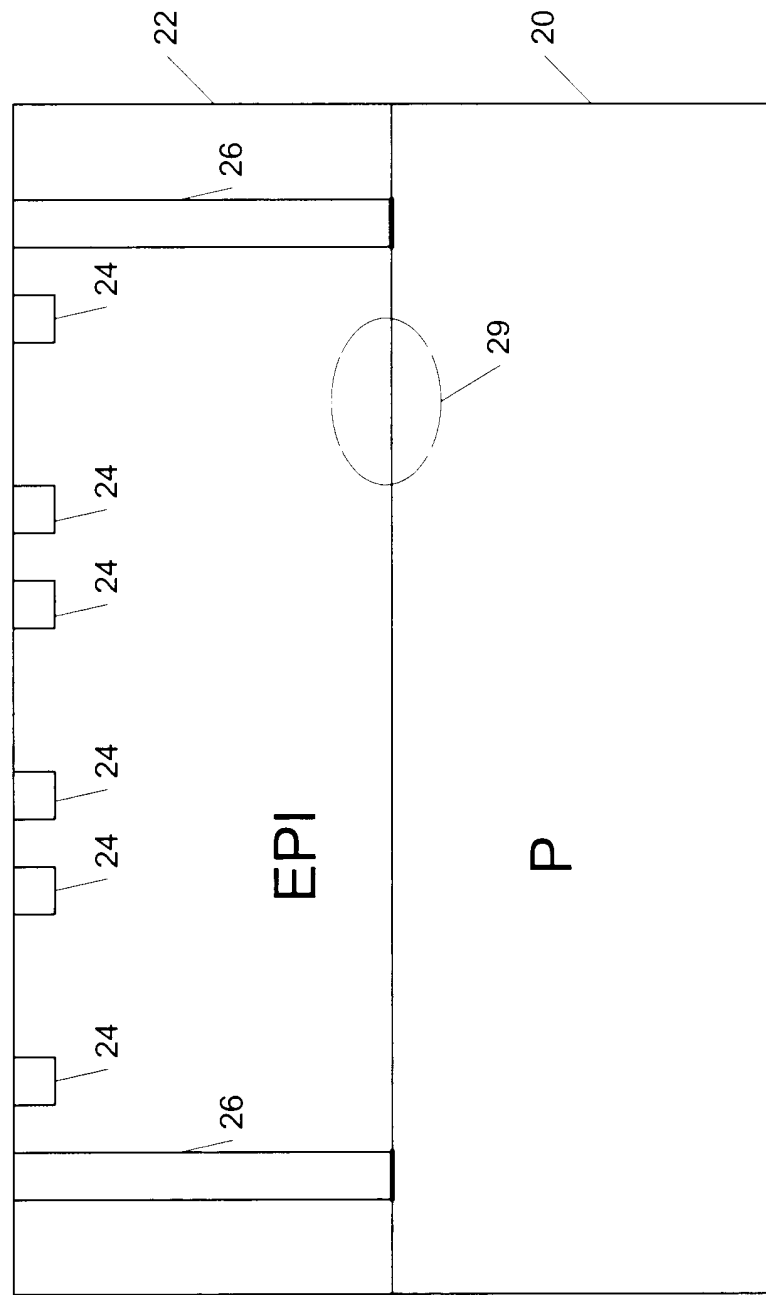


Fig. 2d

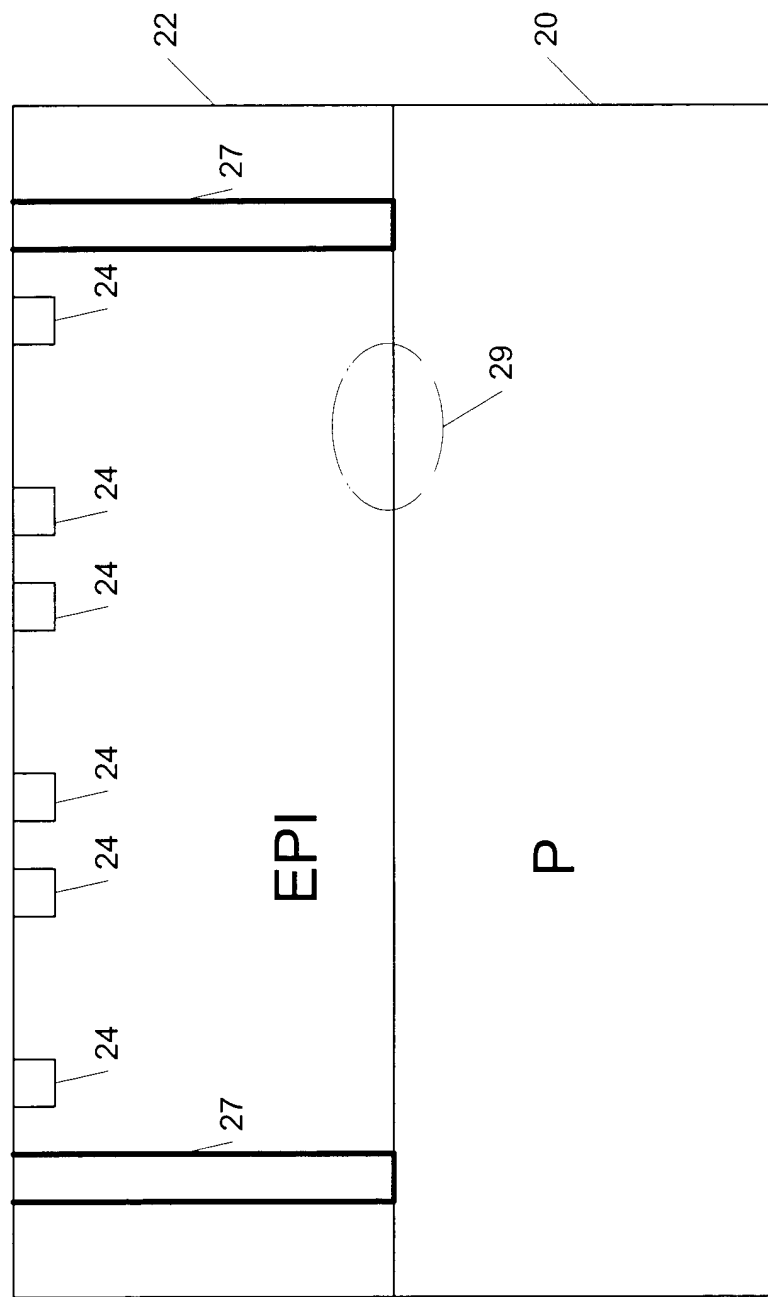


Fig. 2e

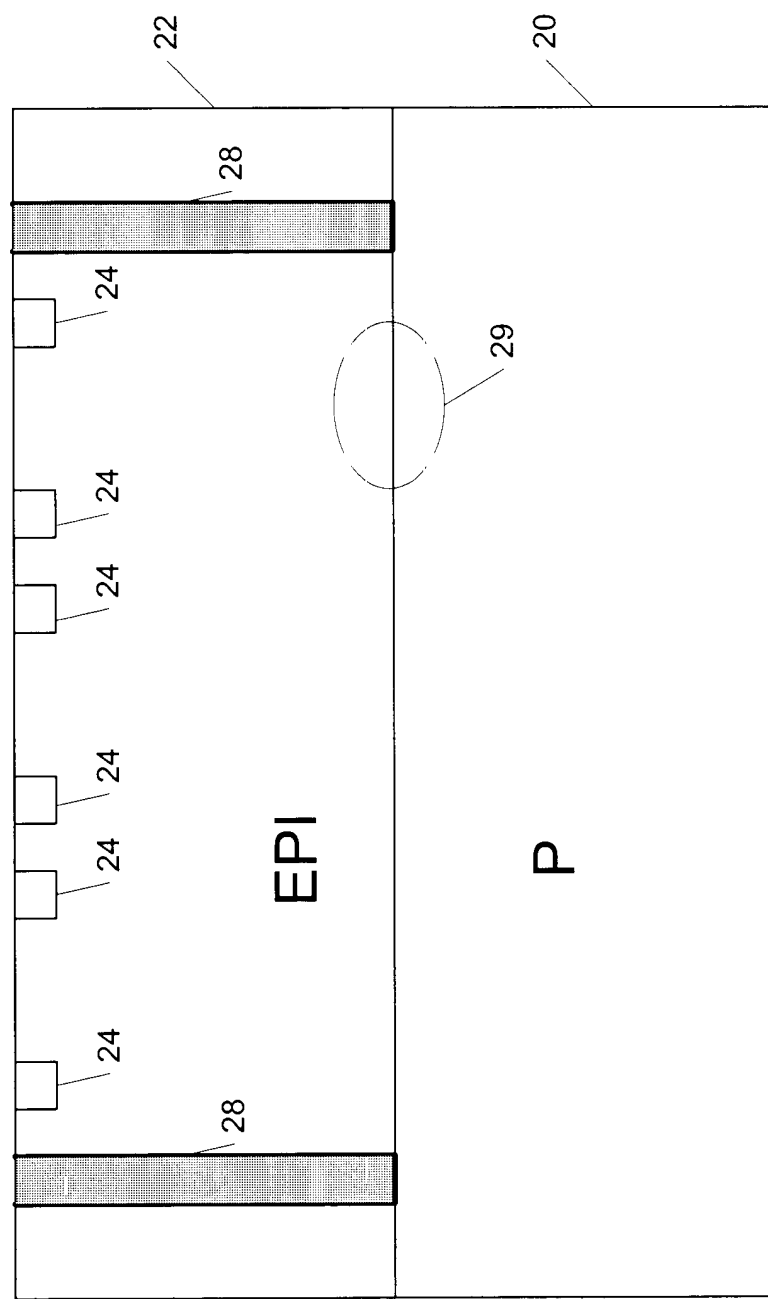


Fig. 2f

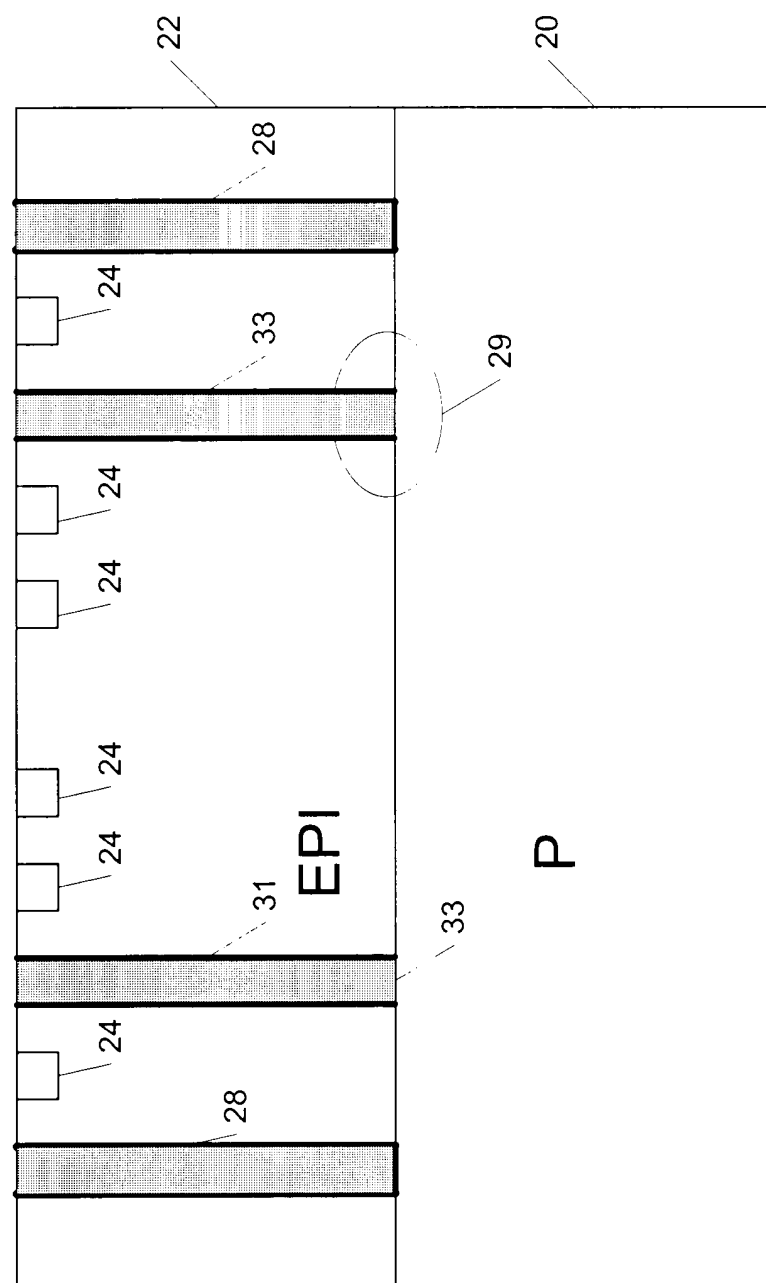


Fig. 29

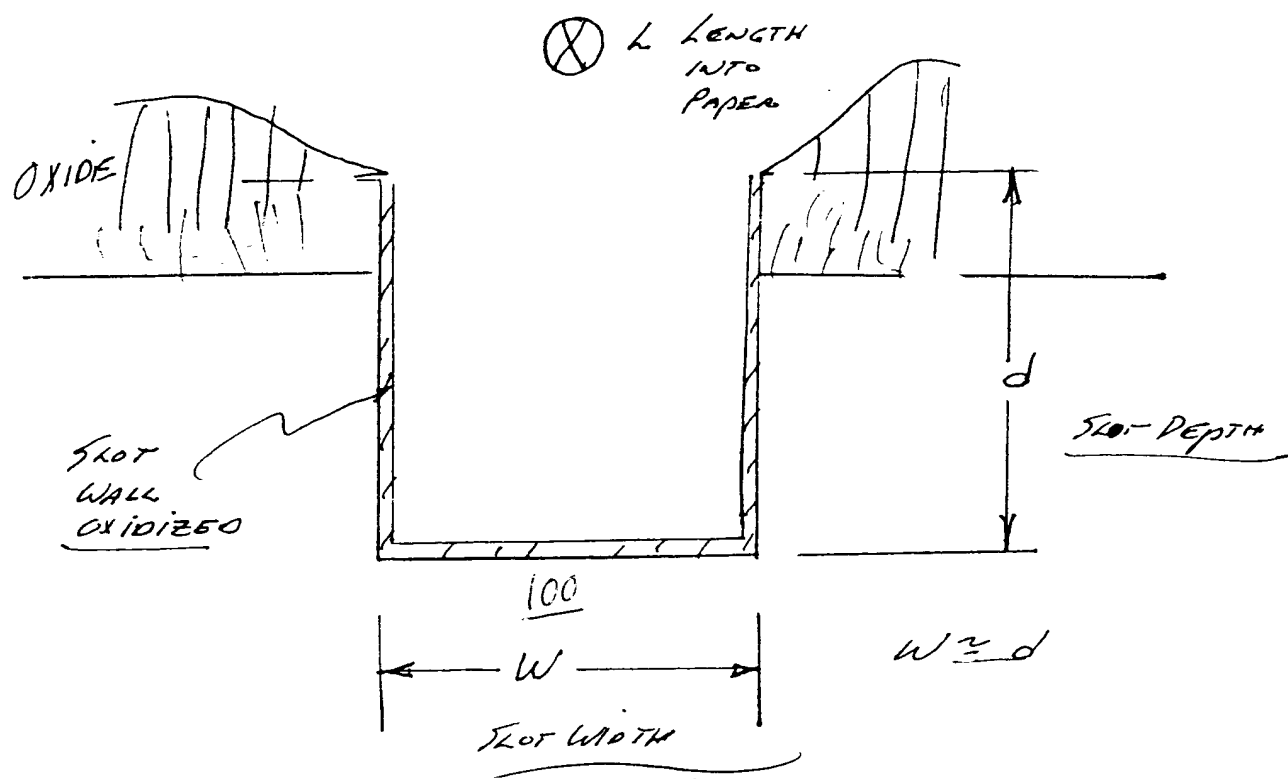


Fig. 3

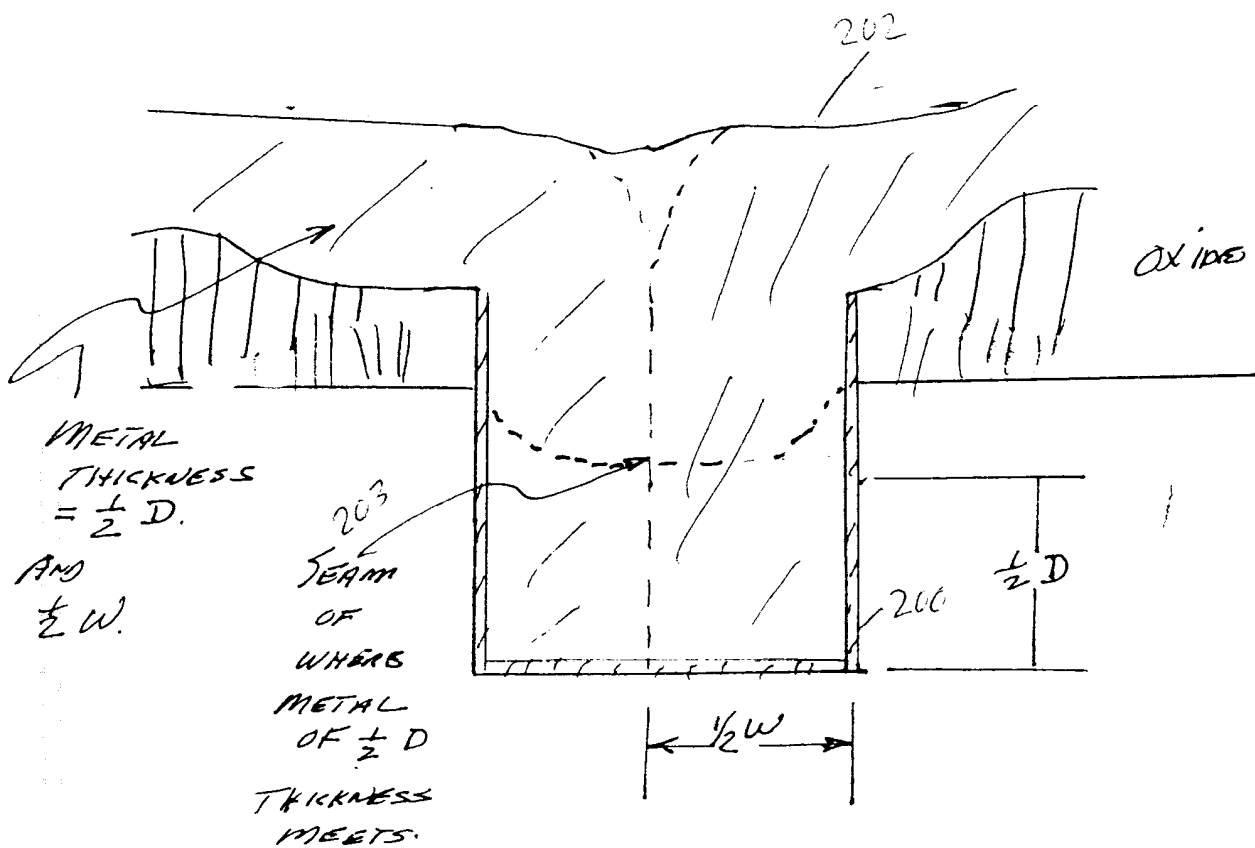
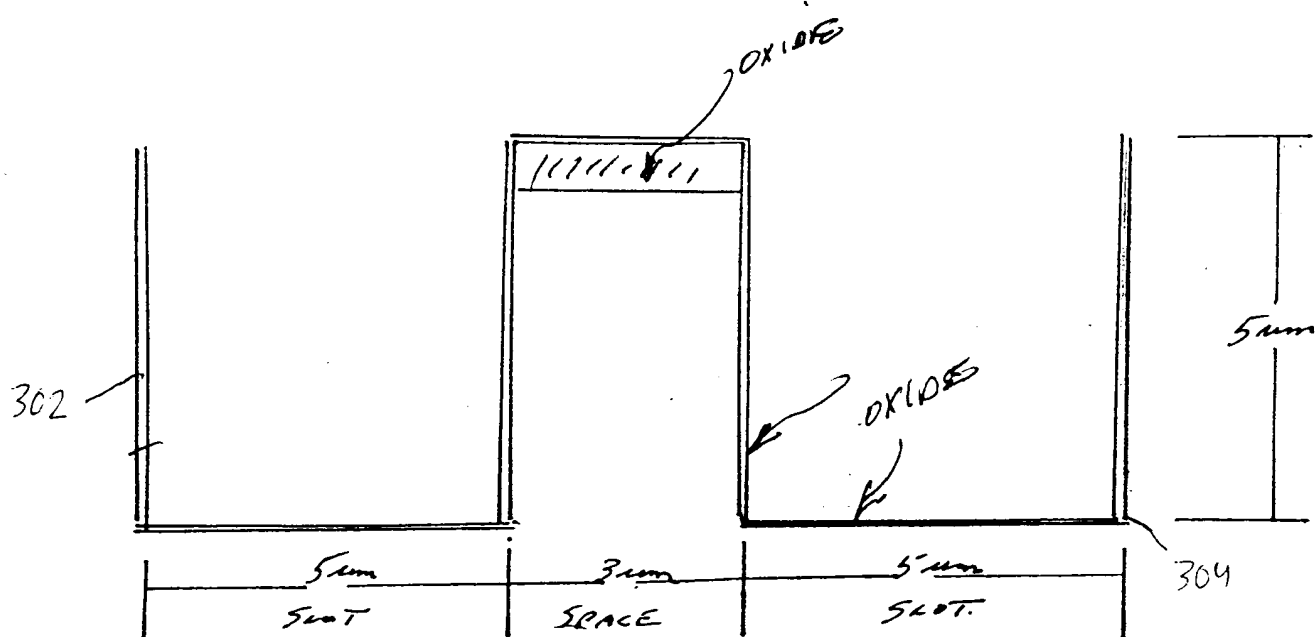
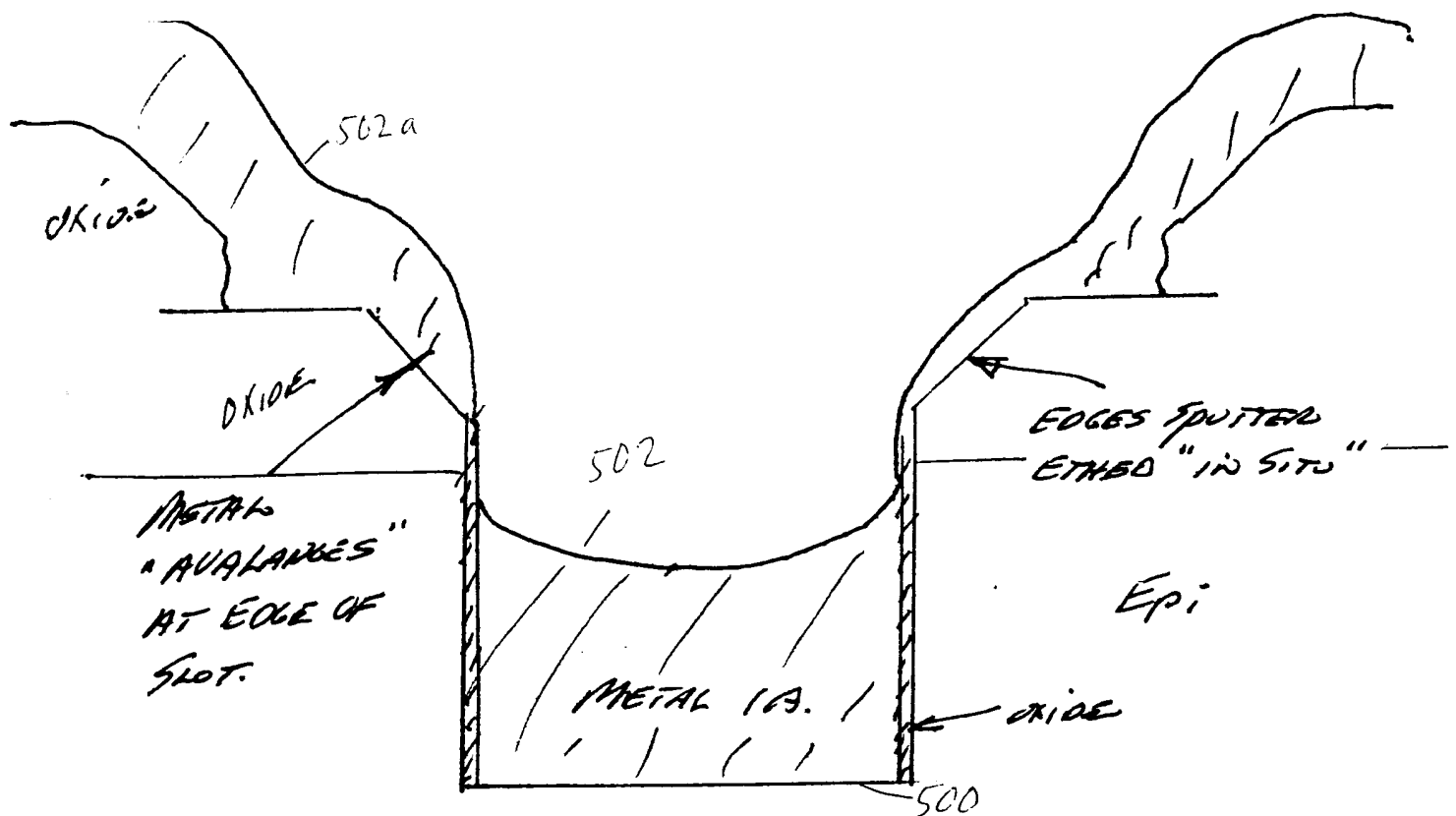


Fig. 4



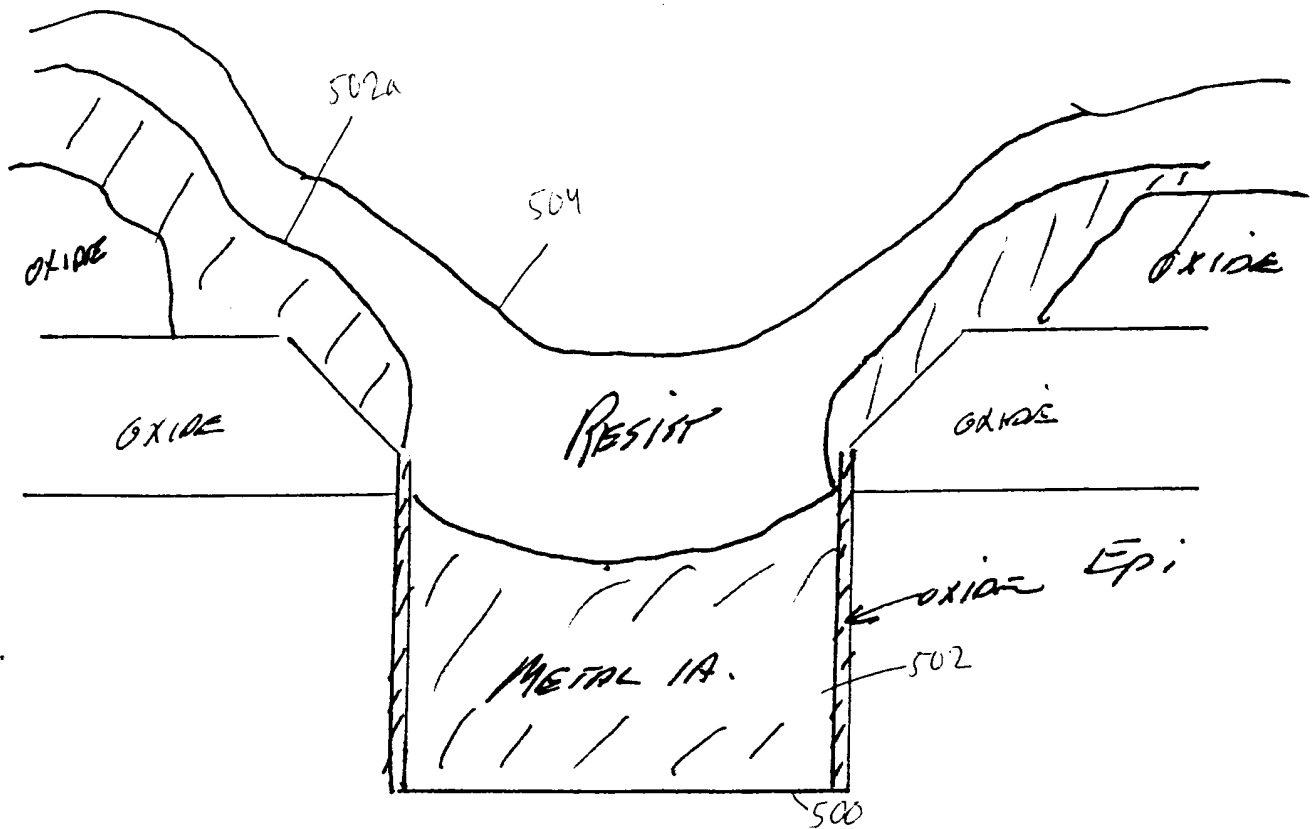
DOUBLE SLOT FOR
DOUBLE WIDTH OF METAL.
3mm SPACE BETWEEN SLOTS

Fig. 4a



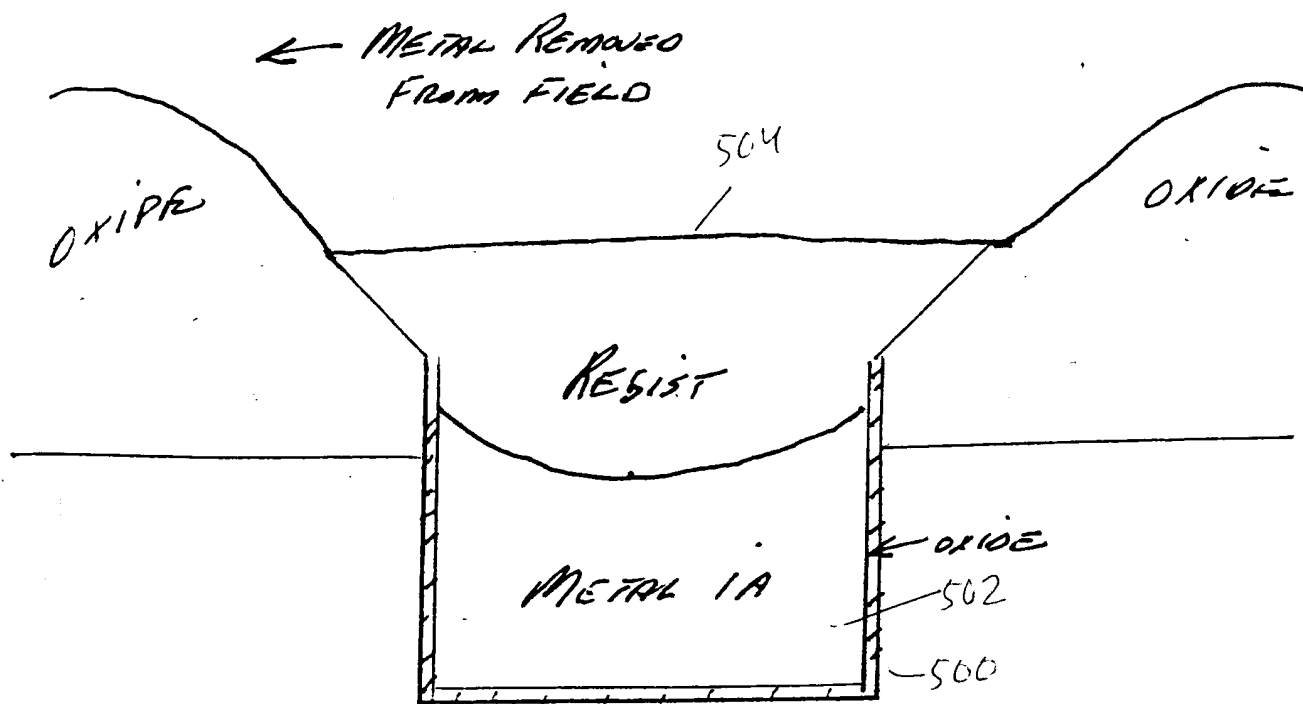
Prior TO METAL 1A BEING
 SPUTTERED, THE EDGES OF THE OXIDES
 ARE SPUTTERED ETCHED "IN SITU" &
 1A DEPOSITED

Fig. 5



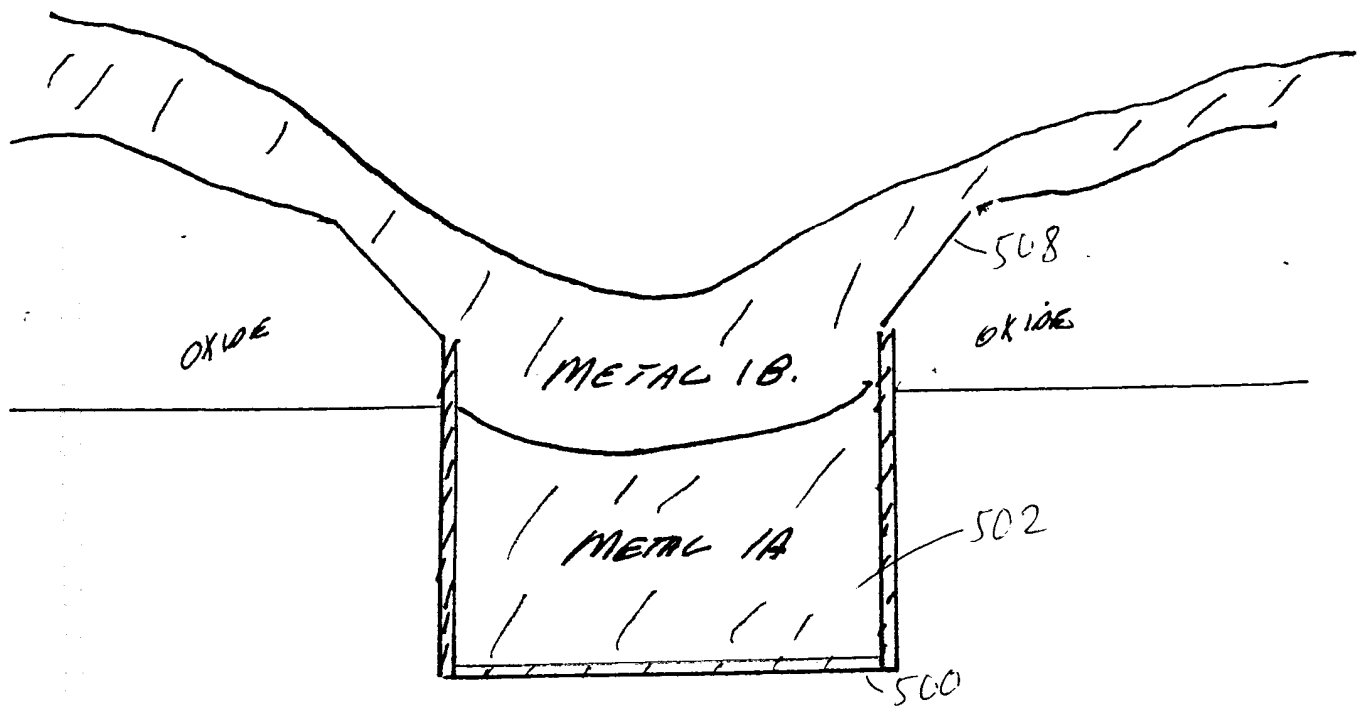
RESIST COATING - THICK IN THE
SLOTS

Fig. 6



RESIST PLASMA ETCHED.
 LEAVING RESIST IN TRENCHES
 FIELD METAL ETCHED OFF.

Fig. 7



RESIST STRIPPED & SECOND
METAL 1B SPUTTER DEPOSITED

Fig. 8

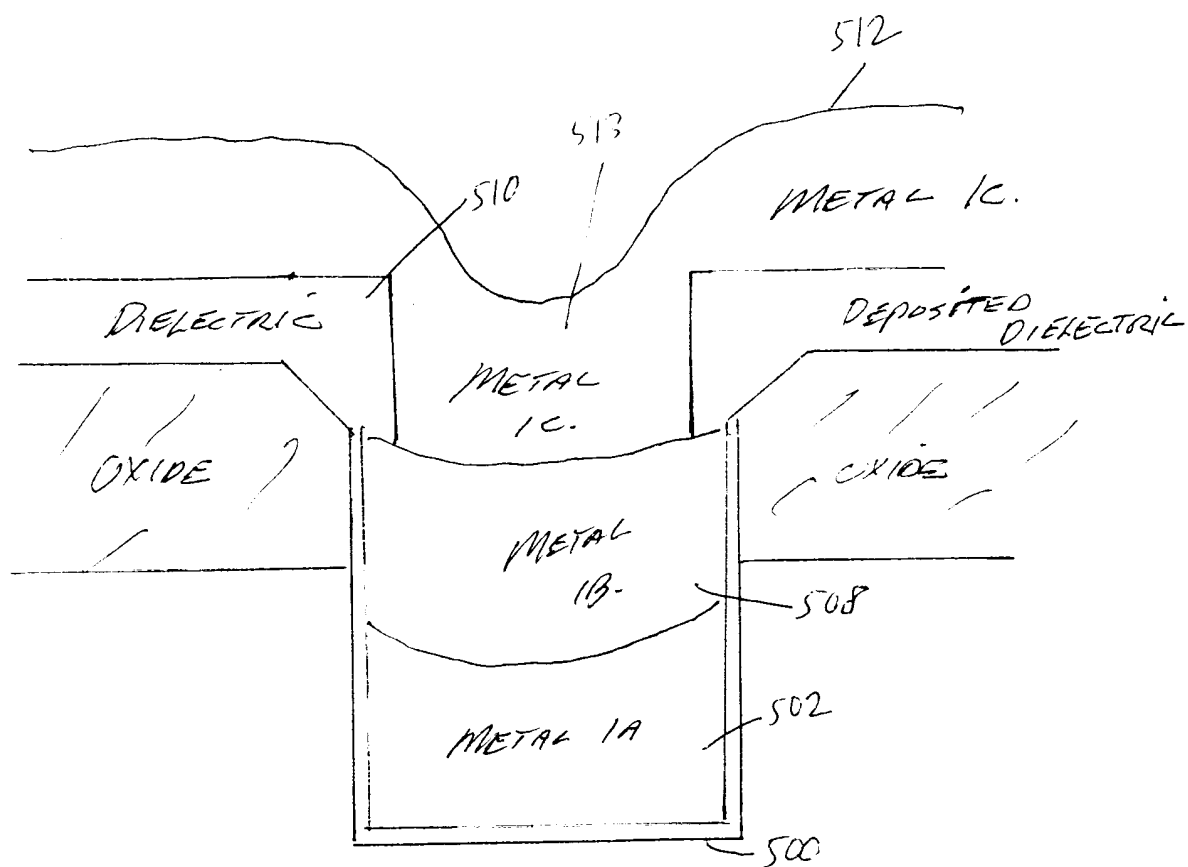


Fig. 9

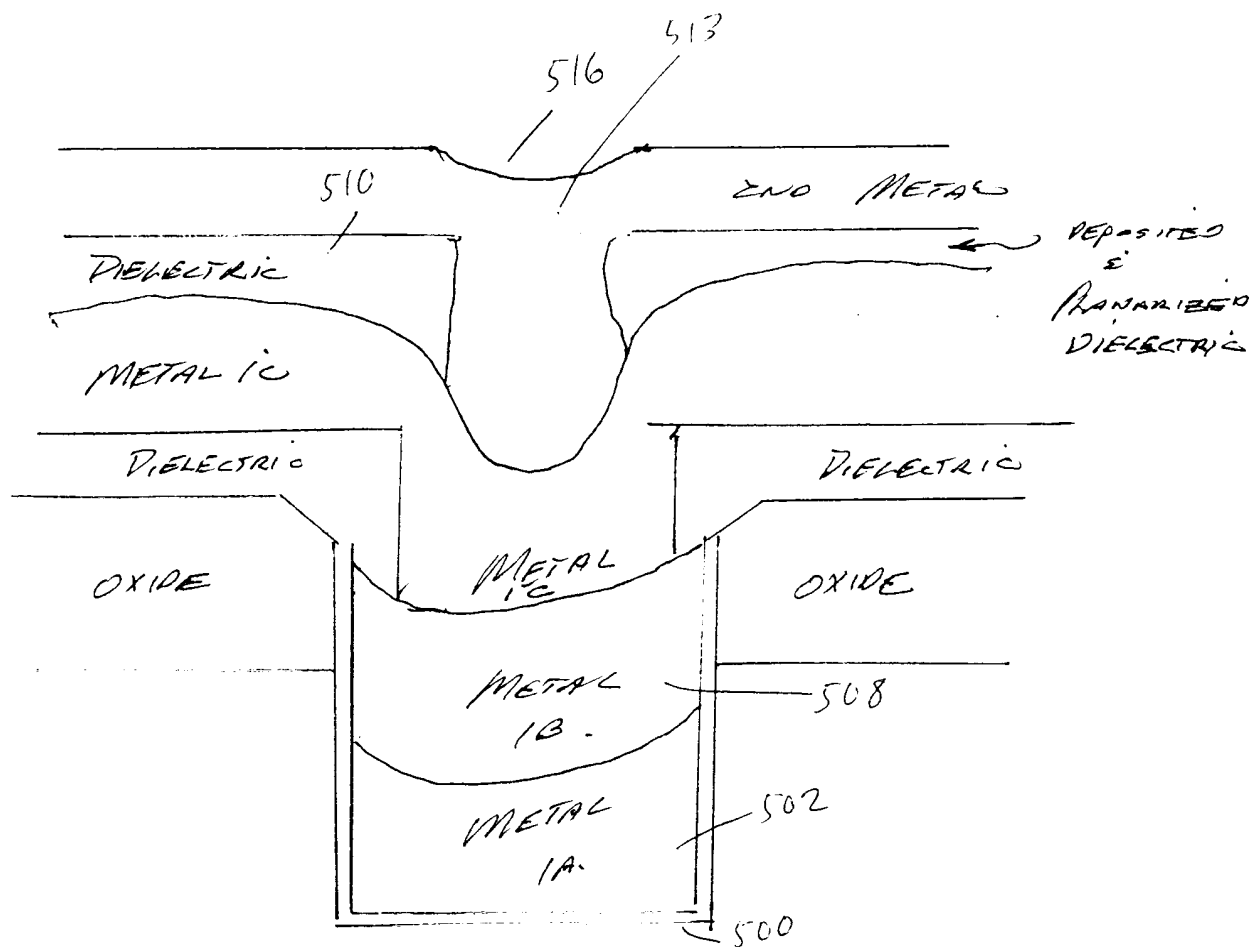
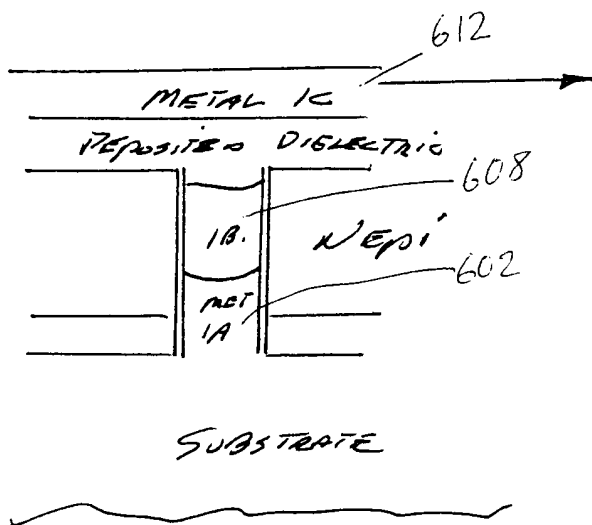


Fig. 10



METAL IC
 CONNECTS AN ISOLATED
 ISLAND TO ADJACENT
 ISOLATED EPI ISLANDS
 AND CROSSES OVER THE
 ISOLATION GROUND
 STRAP BY NOT OPENING
 A VIA IN THIS PORTION
 TO ALLOW IC TO BE
 ISOLATED FROM GROUND.

Fig. 12